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(54) ELECTROTHERMAL MODULE

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(57) ABSTRACT

An electrothermal module includes a first conductive layer, a second conductive layer, and a heat generating layer. The first conductive layer and the second conductive layer respectively include silver metal. The heat generating layer has a first portion, the first portion is disposed between the first conductive layer and the second conductive layer to form an electrothermal conversion portion of the electrothermal module, and the heat generating layer includes a conductive carbon material.

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